

# PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Je-Hun LEE	10/29/2007
Do-Hyun KIM	10/29/2007
Eun-Guk LEE	10/29/2007
Chang-Oh JEONG	10/29/2007
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co. LTD.
Street Address:	416, Maetan-dong, Yeongtong-gu, Suwon-si
City:	Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11930502
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ATTORNEY DOCKET NUMBER:	21C-0486
NAME OF SUBMITTER:	Deidre M. Davis Reg. No. 52,797
Total Attachments: 2 source=assignment#page1.tif source=assignment#page2.tif	

CH \$40.00 11930502

**PATENT**

**500387544**

**REEL: 020042 FRAME: 0501**

### ASSIGNMENT

WHEREAS **I, Je-Hun LEE** of 401, Daeil Villa, #724-12, Mok 4-dong, Yangcheon-gu, Seoul, Korea, **Do-Hyun KIM** of 204-1002, Yuwon 2-cha Apt., #7-2, Dansan-dong 5-ga, Yeongdeungpo-gu, Seoul, Korea, **Eun-Guk LEE** of 404-1802, Geumhwa Maeul Jugong Apt., Sanggal-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Korea, and **Chang-Oh JEONG** of 201-203, Dongsuwon LG Village 2-cha, Mangpo-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

#### **THIN-FILM TRANSISTOR, ARRAY SUBSTRATE HAVING THE THIN-FILM TRANSISTOR AND METHOD OF MANUFACTURING THE ARRAY SUBSTRATE**

which claims priority to Korean Application No. 2007-58353, filed on June 14, 2007 and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **SAMSUNG ELECTRONICS CO., LTD** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea, having a place of business at **416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor,

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications

when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 2007-10-29



Je-Hun LEE

L.S.

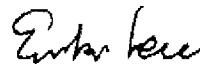
Date: 2007. 10. 29



Do-Hyun KIM

L.S.

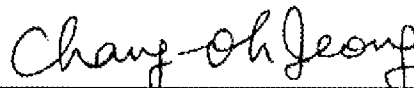
Date: 07. 10. 29



Eun-Guk LEE

L.S.

Date: 2007. 10. 29



Chang-Oh JEONG

L.S.